



Based on IPC J-STD-001 - Requirements for Soldered Electrical and Electronic Assemblies - IPC Training center strongly recommends IKEUCHI's®"E" Dry Fog system



“The Fog Engineers” IKEUCHI EUROPE B.V.

4.2.1 Environmental Controls - The soldering facility should be enclosed, temperature and humidity controlled, and maintained at a positive pressure.

4.2.2 Temperature and Humidity - When humidity decreases to a level of 30% or lower, the Manufacturer **shall (N1D2D3)** verify that electrostatic discharge control is adequate. For process control, more restrictive temperature and humidity limits may be required.

4.2.2.1 Temperature - For operator comfort and solderability maintenance, the temperature should be maintained between 18°C (64,4°F) and 30°C (86°F).

4.2.2.2 Humidity - The range (lower and upper limits) of humidity in the assembly area **shall (N1D2D3)** allow soldering (including solderability maintenance) and assembly materials to function correctly in the process, based on vendor recommendations or documented evidence of process performance. For operator comfort the relative humidity should not exceed 70%.

